IEEE P802.11  
Wireless LANs

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| TGbe Jan-Mar Teleconference Minutes | | | | |
| Date: 2023-04-05 | | | | |
| Author(s): | | | | |
| Name | Affiliation | Address | Phone | email |
| Jason Yuchen Guo | Huawei |  |  | guoyuchen@huawei.com |
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|  |  |  |  |  |

Abstract

This document contains the minutes for the IEEE 802.11 TGbe teleconferences from March 2023 to May 2023.

Revision history:

* Rev0: initial version of the document

Abbreviations:

* C: Comment.
* A: Answer.

# 1st Conf. Call: March 27 (19:00–21:00 ET)–MAC

Please refer to the following link for the minutes

* https://mentor.ieee.org/802.11/dcn/23/11-23-0543-03-00be-minutes-for-tgbe-mac-ad-hoc-teleconferences-in-march-to-may-2023.docx

# 2nd Conf. Call: March 29 (10:00–12:00 ET)–MAC

Please refer to the following link for the minutes

* To be added

# 3rd Conf. Call: April 05 (10:00–12:00 ET)–JOINT

* The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order
* IEEE 802 and 802.11 IPR policy and procedure
  + **Patent Policy: Ways to inform IEEE:**
    - Cause an LOA to be submitted to the IEEE-SA ([patcom@ieee.org](mailto:patcom@ieee.org)); or
    - Provide the chair of this group with the identity of the holder(s) of any and all such claims as soon as possible; or
    - Speak up now and respond to this Call for Potentially Essential Patents

If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group and that are not already the subject of an Accepted Letter of Assurance, please respond at this time by providing relevant information to the WG Chair. **Nobody speaks/writes up**.

* + **Copyright Policy: Participants are advised that**
    - IEEE SA’s copyright policy is described in [Clause 7](https://standards.ieee.org/about/policies/bylaws/sect6-7.html#7) of the IEEE SA Standards Board Bylaws and [Clause 6.1](https://standards.ieee.org/about/policies/opman/sect6.html) of the IEEE SA Standards Board Operations Manual;
    - Any material submitted during standards development, whether verbal, recorded, or in written form, is a Contribution and shall comply with the IEEE SA Copyright Policy
    - **Copyright Policy was presented.**
  + **Patent, Participation, Copyright and policy related subclause:** Please refer to Patent And Procedures
* Attendance reminder.
  + Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
  + Please record your attendance during the conference call by using the IMAT system:
    - 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “<Joint TGbe > conference call that you are attending.
  + If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Jason Y. Guo ([guoyuchen@huawei.com](mailto:guoyuchen@huawei.com)) and Alfred Asterjadhi ([asterjadhi@gmail.com](mailto:asterjadhi@gmail.com))
  + Please ensure that the following information is listed correctly when joining the call:
    - "[voter status] First Name Last Name (Affiliation)"
  + Attendee List

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| Breakout | SA PIN | Timestamp | Name | Affiliation |
| TGbe (Joint) | 135742 | 4/5 | Ajami, Abdel Karim | Qualcomm Technologies, Inc |
| TGbe (Joint) | 78722 | 4/5 | Ansley, Carol | Cox Communications Inc. |
| TGbe (Joint) | 71275 | 4/5 | Asterjadhi, Alfred | Qualcomm Incorporated |
| TGbe (Joint) | 108915 | 4/5 | Baek, SunHee | LG ELECTRONICS |
| TGbe (Joint) | 82782 | 4/5 | baron, stephane | Canon Research Centre France |
| TGbe (Joint) | 83090 | 4/5 | Cao, Rui | NXP Semiconductors |
| TGbe (Joint) | 56788 | 4/5 | Carney, William | Sony Group Corporation |
| TGbe (Joint) | 167397 | 4/5 | Chen, You-Wei | MediaTek Inc. |
| TGbe (Joint) | 173075 | 4/5 | CHENG, yajun | Xiaomi Communications Co., Ltd. |
| TGbe (Joint) | 37892 | 4/5 | CHUN, JINYOUNG | LG ELECTRONICS |
| TGbe (Joint) | 109566 | 4/5 | Chung, Chulho | SAMSUNG |
| TGbe (Joint) | 14719 | 4/5 | Das, Subir | Peraton Labs |
| TGbe (Joint) | 63690 | 4/5 | Dong, Xiandong | Xiaomi Communications Co., Ltd. |
| TGbe (Joint) | 146634 | 4/5 | Fan, Shuang | Sanechips Technology Co., Ltd. |
| TGbe (Joint) | 100055 | 4/5 | Fang, Juan | Intel |
| TGbe (Joint) | 116633 | 4/5 | Fang, Yonggang | Mediatek |
| TGbe (Joint) | 8114 | 4/5 | Fischer, Matthew | Broadcom Corporation |
| TGbe (Joint) | 169410 | 4/5 | Fujimori, Yuki | Canon Research Centre France |
| TGbe (Joint) | 116223 | 4/5 | Gu, Xiangxin | Unisoc |
| TGbe (Joint) | 148342 | 4/5 | Gupta, Binita | Meta Platforms, Inc. |
| TGbe (Joint) | 83911 | 4/5 | Handte, Thomas | Sony Corporation |
| TGbe (Joint) | 77458 | 4/5 | Huang, Po-Kai | Intel |
| TGbe (Joint) | 12865 | 4/5 | Kakani, Naveen | Qualcomm Incorporated |
| TGbe (Joint) | 109532 | 4/5 | Kamel, Mahmoud | InterDigital, Inc. |
| TGbe (Joint) | 185857 | 4/5 | Kim, Geon Hwan | LG ELECTRONICS |
| TGbe (Joint) | 54245 | 4/5 | Kim, Jeongki | Ofinno |
| TGbe (Joint) | 55256 | 4/5 | Kim, Youhan | Qualcomm Technologies, Inc. |
| TGbe (Joint) | 74993 | 4/5 | Kishida, Akira | Nippon Telegraph and Telephone Corporation (NTT) |
| TGbe (Joint) | 128277 | 4/5 | Koundourakis, Michail | Samsung Cambridge Solution Centre |
| TGbe (Joint) | 128973 | 4/5 | Kreishan, Loay | Charter Communications |
| TGbe (Joint) | 76516 | 4/5 | Lalam, Massinissa | SAGEMCOM BROADBAND SAS |
| TGbe (Joint) | 53490 | 4/5 | Lanante, Leonardo | Ofinno |
| TGbe (Joint) | 35373 | 4/5 | Lee, Wookbong | Apple Inc. |
| TGbe (Joint) | 65113 | 4/5 | Li, Weiyi | Spreadtrum |
| TGbe (Joint) | 143102 | 4/5 | Li, Yapu | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint) | 72713 | 4/5 | Lim, Dong Guk | LG ELECTRONICS |
| TGbe (Joint) | 126156 | 4/5 | Lin, Zinan | InterDigital, Inc. |
| TGbe (Joint) | 109417 | 4/5 | Lorgeoux, Mikael | Canon Research Centre France |
| TGbe (Joint) | 107965 | 4/5 | Lou, Hanqing | InterDigital, Inc. |
| TGbe (Joint) | 98886 | 4/5 | Lu, Liuming | Guangdong OPPO Mobile Telecommunications Corp.,Ltd |
| TGbe (Joint) | 134452 | 4/5 | Ma, Yongsen | SAMSUNG ELECTRONICS |
| TGbe (Joint) | 171674 | 4/5 | MAO, ZHI | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 13492 | 4/5 | McCann, Stephen | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 131432 | 4/5 | Nayak, Peshal | Samsung Research America |
| TGbe (Joint) | 93668 | 4/5 | Ng, Boon Loong | Samsung Research America |
| TGbe (Joint) | 164905 | 4/5 | Park, Sungjin | Senscomm |
| TGbe (Joint) | 82004 | 4/5 | Patil, Abhishek | Qualcomm Incorporated |
| TGbe (Joint) | 94019 | 4/5 | Patwardhan, Gaurav | Hewlett Packard Enterprise |
| TGbe (Joint) | 51587 | 4/5 | Petrick, Albert | InterDigital, Inc. |
| TGbe (Joint) | 179197 | 4/5 | Qi, Yue | Samsung Research America |
| TGbe (Joint) | 173487 | 4/5 | Quan, Yingqiao | Unisoc |
| TGbe (Joint) | 131430 | 4/5 | Ratnam, Vishnu | Samsung Research America |
| TGbe (Joint) | 136743 | 4/5 | Ryu, Kiseon | NXP Semiconductors |
| TGbe (Joint) | 60570 | 4/5 | Schelstraete, Sigurd | MaxLinear |
| TGbe (Joint) | 91082 | 4/5 | Sevin, Julien | Canon Research Centre France |
| TGbe (Joint) | 124960 | 4/5 | Shafin, Rubayet | Samsung Research America |
| TGbe (Joint) | 66611 | 4/5 | SUH, JUNG HOON | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 72083 | 4/5 | Wang, Chao Chun | MediaTek Inc. |
| TGbe (Joint) | 55283 | 4/5 | Wei, Dong | NXP Semiconductors |
| TGbe (Joint) | 108593 | 4/5 | Wullert, John | Peraton Labs |
| TGbe (Joint) | 89721 | 4/5 | Yano, Kazuto | Advanced Telecommunications Research Institute International (ATR) |
| TGbe (Joint) | 102774 | 4/5 | Yi, Yongjiang | Spreadtrum Communication USA, Inc |
| TGbe (Joint) | 182012 | 4/5 | Yoon, Yelin | LG ELECTRONICS |
| TGbe (Joint) | 12710 | 4/5 | Zaman, Malia | IEEE Standards Association (IEEE-SA) |
| TGbe (Joint) | 195888 | 4/5 | Zhao, Yue | Huawei Technologies Co., Ltd |
| TGbe (Joint) | 32987 | 4/5 | Zhou, Lei | H3C Technologies Co., Limited |

* **Announcements:** Please send an email to Matt to register the MAC ad hoc meeting in May.
* Agenda
  + CR Submissions:
    - 516r0 LB271 CR for 9 3 1 22 2 Yanjun Sun [11C]
  + MAC CR Submissions:
    - [329r0](https://mentor.ieee.org/802.11/dcn/23/11-23-0329-00-00be-resolution-of-general-epcs-related-cids-lb271.docx) Resolution of General EPCS-Related CIDs John Wullert [18C]
    - [330r1](https://mentor.ieee.org/802.11/dcn/23/11-23-0330-01-00be-resolution-of-epcs-related-cids-in-clause-35-16-lb271.docx) Resolution of EPCS-Related CIDs in Clause 35.16 John Wullert [18C]
    - [387r0](https://mentor.ieee.org/802.11/dcn/23/11-23-0387-00-00be-lb271-cr-for-subclause-35-3-12-6.docx) LB271 CR for subclause 35.3.12.6 Ming Gan [8C]
  + Discussions
    - Doc. 558, 517 are added
  + Agenda approved with unanimous consent
* **Technical contributions**
  + 516r0 LB271 CR for 9 3 1 22 2 Yanjun Sun

Discussions: editorial changes

**SP:** Do you agree to resolve the following CIDs listed in 11-22/516r2 and incorporate the text changes into the latest TGbe draft?

         15899,17430,16248,16249,15900,17431,17432,17433,17434,17435,17436

Discussion: None.

Result: No objection

* + 558r2 LB 271 CR for 35.7.1 Zinan Lin

C: CID 17980, we talk about sounding sequence, instead of sounding mechanism.

C: CID 17272, “and/or” should be “or”

**SP:** Do you agree to resolve the following CIDs listed in 11-23/558r3 and incorporate the text changes into the latest TGbe draft?

         17041, 17271, 17980, 17042, 17272

Discussion: None.

Result: No objection

* + 517r0 LB271 CR for 9 3 1 22 3 Yanjun Sun

C: editorial suggestions.

**SP:** Do you agree to resolve the following CIDs listed in 11-23/0517r2 and incorporate the text changes into the latest TGbe draft?

         17903,17437,17438,17439,17440,17441,17442,16129,17443,17444,17445

Discussion: None.

Result: No objection

* + [329r0](https://mentor.ieee.org/802.11/dcn/23/11-23-0329-00-00be-resolution-of-general-epcs-related-cids-lb271.docx) Resolution of General EPCS-Related CIDs John Wullert

C: editorial suggestions.

**SP:** Do you agree to resolve the following CIDs listed in 11-23/0329r1 and incorporate the text changes into the latest TGbe draft?

        15942, 15354, 15693, 15694, 16367, 17965, 17673, 15371, 15370, 17675, 17676, 17781, 17782, 15383, 15384, 15385, 15386

Discussion: None.

Result: No objection

* + [330r1](https://mentor.ieee.org/802.11/dcn/23/11-23-0330-01-00be-resolution-of-epcs-related-cids-in-clause-35-16-lb271.docx) Resolution of EPCS-Related CIDs in Clause 35.16 John Wullert

C: CID 15426, it seems we don’t need the note since it is the AP’s choice on how to set the EDCA parameters and MU EDCA parameters. This CID is deferred after discussion. Same for 15425 and 15429.

C: defer 15427.

C: defer 15442.

**SP:** Do you agree to resolve the following CIDs listed in 11-23/0330r2 and incorporate the text changes into the latest TGbe draft?

         16702, 17371, 15428, 15430, 15431, 15432, 15584, 15433, 15434, 15435, 15436, 15441

Discussion: None.

Result: No objection

The chair asked if there’s any objection to add doc. 11-23/499 and 11-23/437 to the queue.

No objection.

* + Agenda discussion: doc. 387 is deferred to the next meeting. Doc. 499 and doc. 437 are added.
  + 499r1 LB271 CR CL9 CL35 MLTI editorial Minyoung Park

Discussion: None.

**SP:** Do you agree to resolve the following CIDs listed in 11-23/0499r1 and incorporate the text changes into the latest TGbe draft?

 16601 16822 16823 18276 16530 16825 16826 15086 16602 15826 17293

Discussion: None.

Result: No objection

* + 437r1

C: for the transition delay, it should apply to both the AP and non-AP

C: change “not” to “neither”

Unfinished contribution.

* AoB: None
* Recessed at 11:59